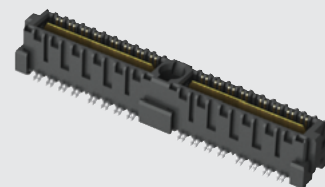


QMS-026-06.75-L-D-A



(0,635 mm) .025"

QMS SERIES

RUGGED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:

Liquid Crystal Polymer

Terminal & Ground

Plane Material:

Phosphor Bronze

Plating:

Au over 50µ" (1,27 µm) Ni

(Tin on Ground Plane Tail)

Current Rating:

Contact:

2.6 A per pin

(1 pin powered per row)

Ground Plane:

15.7 A per ground plane

(1 ground plane powered)

Voltage Rating:

300 VAC mated with QFS

Operating Temp:

-55°C to +125°C

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (026-052)

(0,15 mm) .006" max (078)

Board Stacking:

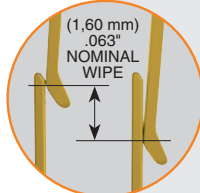
For applications requiring more than two connectors per board, contact ipg@samtec.com

Board Mates:

QFS

Cable Mates:

6QCD



Integral metal plane for power or ground

Increased insertion depth for rugged applications

QMS/QFS 10 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	8 GHz / 16 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	7.5 GHz / 15 Gbps	9 GHz / 18 Gbps

*Performance data includes effects of a non-optimized PCB.

**Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?QMS or contact sig@samtec.com

ALSO AVAILABLE (MOQ Required)

- Other platings
 - Guide Posts
 - Without PCB Alignment Pins (05.75 and 06.75 only)
 - Hot Pluggable
 - 64 (-DP) and 104 positions per row
- Contact Samtec.

QMS — PINS PER ROW NO. OF PAIRS — LEAD STYLE — PLATING OPTION — TYPE — A — OTHER OPTION

-026, -052, -078
(52 total pins per bank = -D)

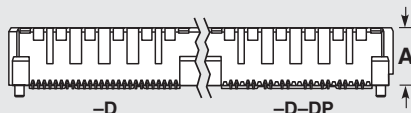
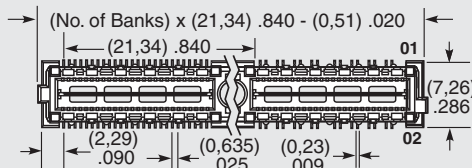
-016, -032, -048
(16 pairs per bank = -D-DP)

(-078 & -048 Not available with -09.75 lead style)

Specify LEAD STYLE from chart

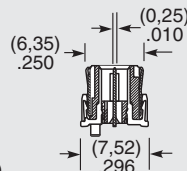
LEAD STYLE	A	MATED HEIGHT*	
		QFS LEAD STYLE -04.25	-06.25
-05.75	(5,38) .212	10 mm	12 mm
-06.75	(6,35) .250	11 mm	13 mm
-09.75	(9,35) .368	14 mm	16 mm

*Processing conditions will affect mated height.



-L
(-05.75 and -06.75 lead style only)
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

-SL
(-09.75 lead style only)
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

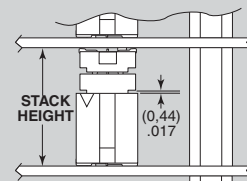


-D
= Single-Ended

-D-DP
= Differential Pair

-K
= (5,50 mm) .217" DIA Polyimide film Pick & Place Pad

APPLICATION



Requires Standoff
SO-1524-03-01-01-L for 15,24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

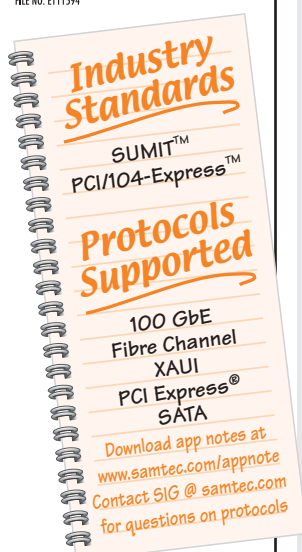
INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15,24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15,24 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594



Note: Some lengths, styles and options are non-standard, non-returnable.